Lithium Doped Polyethylene-Glycol-Based Thermal Int
Contact Conductance

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Citation Report

#	Article	IF	Citations
1	Carbon black dispersions as thermal pastes that surpass solder in providing high thermal contact conductance. Carbon, 2003, 41, 2459-2469.	5.4	126
2	Carbon black dispersions and carbonâ€“silver combinations as thermal pastes that surpass commercial silver and ceramic pastes in providing high thermal contact conductance. Carbon, 2004, 42, 2323-2327.	5.4	52
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4	Non-adiabatic thin-film (chip) nanocalorimetry. Thermochimica Acta, 2005, 432, 177-185.	1.2	149
5	Carbon-black thixotropic thermal pastes for improving thermal contacts. Journal of Electronic Materials, 2005, 34, 1336-1341.	1.0	32
6	Boron Nitride Particle Filled Paraffin Wax as a Phase-Change Thermal Interface Material. Journal of Electronic Packaging, Transactions of the ASME, 2006, 128, 319-323.	1.2	15
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10	Effect of carbon black structure on the effectiveness of carbon black thermal interface pastes. Carbon, 2007, 45, 2922-2931.	5.4	45
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12	Nanostructured fumed metal oxides for thermal interface pastes. Journal of Materials Science, 2007, 42, 9245-9255.	1.7	29
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16	Chip calorimetry for fast cooling and thin films: a review. Frontiers of Chemistry in China: Selected Publications From Chinese Universities, 2009, 4, 229-248.	0.4	16
17	Rheological Behavior of Thermal Interface Pastes. Journal of Electronic Materials, 2009, 38, 2069-2084.	1.0	11
18	Thermal Conductivity of Diamond-Containing Grease. Journal of Electronic Packaging, Transactions of the ASME, 2010, 132, .	1.2	4

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19	Enhancement of the thermal conductivity of aluminum oxideâ€"epoxy terminated poly(dimethyl) Tj ETQq0 0 0 rgBT /Overlock 10 Tf 50 7	1.7	37
20	Flexible graphite modified by carbon black paste for use as a thermal interface material. Carbon, 2011, 49, 1075-1086.	5.4	38
21	The effects of functionalized graphene nanosheets on the thermal and mechanical properties of epoxy composites for anisotropic conductive adhesives (ACAs). Microelectronics Reliability, 2012, 52, 595-602.	0.9	97
22	Thermal and electrical conductivity of Al(OH)3 covered graphene oxide nanosheet/epoxy composites. Journal of Materials Science, 2012, 47, 1418-1426.	1.7	45
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